**Bidirectional ESD and Transient Voltage Protection** 

SDxxxxD32G SOD323

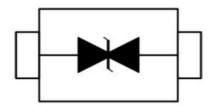


### **Description**

The SDxxxxD32G series is designed for applications requiring transient overvoltage protection capability. They are intended for use in voltage and ESD sensitive equipment such as computers, printers, business machines, communication systems, medical equipment and other applications. These devices are ideal for situations where board space is at a premium.

This series has been specifically designed to protect sensitive components which are connected to power, data and transmission lines from overvoltage caused by ESD (electrostatic discharge), CDE (Cable Discharge Events), and EFT (electrical fast transients).

## **Pinout and Functional Block Diagram**



#### **Applications**

- Networking and Telecom
- Microprocessor based equipment
- Personal Digital Assistants (PDA's)
- Notebooks, Desktops, and Servers
- Cell Phone Handsets and Accessories
- Portable Instrumentation
- Serial and Parallel Ports
- Peripherals

#### **Features**

- IEC61000-4-2 (ESD) ±30 kV (Air), ±30 kV (Contact)
- IEC61000-4-4 (EFT) 40 A (5 / 50 ns)
- Peak Power Dissipation: 350 W@8 / 20 μs
- Protects One I/O Line (Bidirectional)
- Low Clamping Voltage
- Low Leakage Current
- High Temperature to Reflow Soldering Guaranteed: 260
   °C / 10 sec
- MSL1
- Flammability Rating: UL 94 V-0
- Halogen Free and RoHS Compliant

#### **Order Information**

Туре	Package	Marking Code	Delivery Form	Delivery Quantity
SDxxxxD32G	SOD323	Refer to next page	7" T&R	3000 PCS

## **Limiting Values**

(T<sub>A</sub> = 25 °C, unless otherwise specified)

Symbol	Parameter	Conditions	Min	Max	Unit
		IEC 61000-4-2; Contact Discharge	-	30	kV
V <sub>ESD</sub>	Electrostatic Discharge Voltage	IEC 61000-4-2; Air Discharge		30	kV
P <sub>PP</sub>	Peak Pulse Power (8 / 20 μs)	-		350	W
T <sub>A</sub>	Operating Temperature Range	-	-55	150	°C
T <sub>stg</sub>	Storage Temperature Range	-	-55	150	°C

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### **Electrical Characteristics**

(T<sub>A</sub> = 25 °C, unless otherwise specified)

Part Number	Device Marking	V <sub>RWM</sub>	V <sub>B</sub>	I <sub>T</sub>	V <sub>c</sub> @1A	(V)		I <sub>R</sub>	CJ
	Code	(V)	(V)	(mA)	(V)			(µA)	(pF)
		(max.)	(min.)		(max.)	(max.)	(@A)	(max.)	(max.)
SD0320D32G	2A	3.3	4.0	1	7.5	16.0	20	40	450
SD0517D32G	2B	5.0	6.0	1	9.8	18.0	17	10	200
SD0815D32G	2C	8.0	8.5	1	13.4	24.0	15	2	120
SD1211D32G	2D	12.0	13.3	1	19.0	32.0	11	1	75
SD1510D32G	2J	15.0	16.7	1	24.0	38.0	10	1	68
SD1809D32G	2K	18.0	20.0	1	29.0	45.0	9	1	57
SD2008D32G	2L	20.0	22.3	1	35.0	50.0	8	1	52
SD2407D32G	2H	24.0	26.7	1	43.0	52.0	7	1	50
SD3605D32G	2N	36.0	40.0	1	60.0	75.0	5	1	35

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#### **Performance Curve for Reference**

(T<sub>A</sub>=25 °C unless otherwise noted)

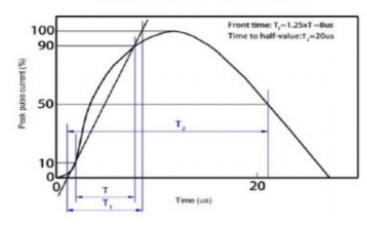


FIGURE 1 8 / 20 µS Waveform Per IEC61000-4-5

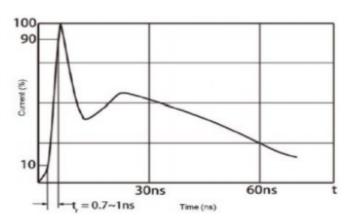


FIGURE 2
Contact Discharge Current Waveform Per IEC 61000-4-2

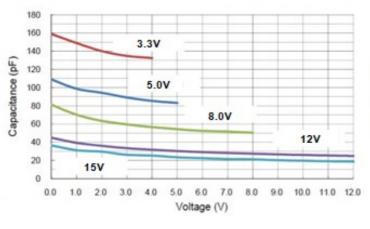


FIGURE 3
Voltage VS. Capacitance

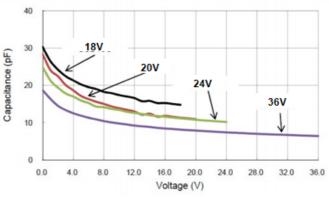


FIGURE 4
Voltage VS. Capacitance

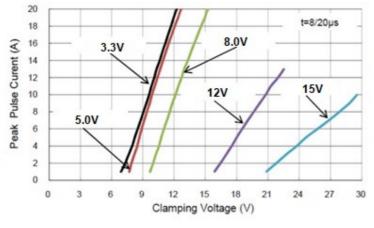


FIGURE 5
Clamping Voltage VS. Peak Pulse Current

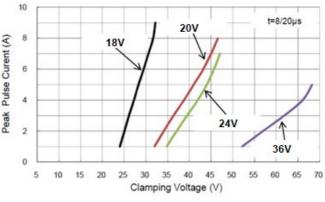
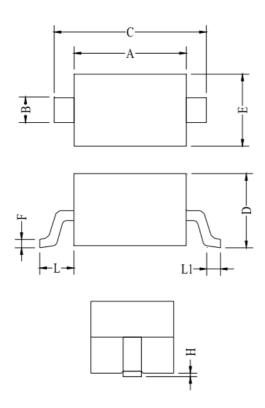


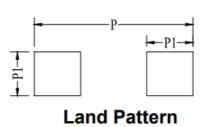
FIGURE 6
Clamping Voltage VS. Peak Pulse Current

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# Package Dimensions - SOD323





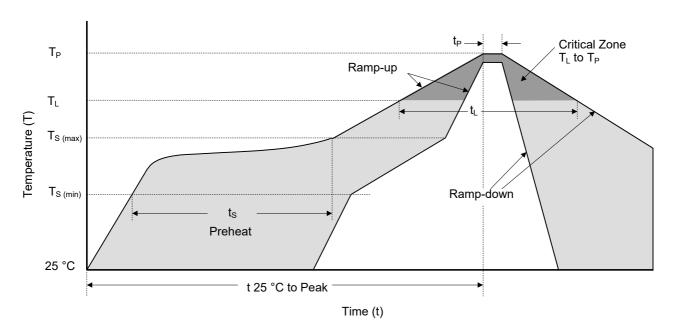
Symbol	Millimet	ers	Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	1.60	1.80	0.063	0.071	
В	0.25	0.40	0.010	0.016	
С	2.30	2.80	0.091	0.110	
D	0.80	1.10	0.031	0.043	
E	1.20	1.40	0.047	0.055	
F	0.08	0.18	0.003	0.007	
L	0.475 R	Ref.	0.019 Ref.		
L1	0.25	0.40	0.010	0.016	
Н	0.00	0.14	0.000	0.006	
Р	3.00	)	0	.118	
P1	0.80		С	0.031	

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# **Soldering Parameters**



Reflowing Condition

Reflow Solderin	Lead-Free Assembly		
Pre-heat	Temperature Min (T <sub>S (min)</sub> )	150 °C	
	Temperature Max (T <sub>S (max)</sub> )	200 °C	
	Time (min to max) (t₅)	60 ~ 120 seconds	
Average Ramp Up Rate (Li	Average Ramp Up Rate (Liquidus Temp (TL) to Peak		
T <sub>s</sub> (max) to T <sub>L</sub>	T <sub>S</sub> (max) to T <sub>L</sub> Ramp-up Rate		
	Temperature (T <sub>L</sub> ) (Liquidus)	217 °C	
Reflow	Time (min to max) (t <sub>L</sub> )	60 ~ 150 seconds	
Peak Tempe	260 <sup>+0/-5</sup> °C		
Time of within 5 °C of Actu	20 ~ 40 seconds		
Ramp-do	6 °C / second max.		
Time from 25 °C to	8 Minutes max.		
Do Not	260 °C		

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## **Usage**

- 1. TVS must be operated in the specified ambient temp.
- 2. Do not clean the TVS with strong polar solvent such as ketone, esters, benzene and halogenated hydrocarbon, to avoid damaging the encapsulating layer.
- 3. Please do not apply severe vibration, shock or pressure to TVS, to avoid element cracking.

### Replacement

- 1. If TVS is visually damaged, please replace it.
- 2. TVS is a non-repairable product. For safety sake, please use equivalent TVS for replacement.

## Storage

- 1. Storage Temp. Range: (-55 to 150) °C.
- 2. Do not store the TVS at the high temp., high humidity or corrosive gas environment, to avoid influencing the solder- ability of the lead wires. The product shall be used up within 1 year after receiving the goods.

#### **Environmental Conditions**

- 1. TVS should not be exposed to the open air, nor direct sunshine.
- 2. TVS should avoid rain, water vapor or other condition of high temp. and high humidity.
- 3. TVS should avoid sand dust, salt mist, or other harmful gases.

## Max. Typical Capacitance of TVS

1. The typical capacitance of TVS is listed in the specifications. Designers may refer to it when designing TVS in High frequency circuit.

#### Installation Mechanical Stress

- 1. Do not knock TVS when installing, to avoid mechanical damage.
- 2. Please do not apply severe vibration, shock or pressure to TVS, to avoid surface resin or element cracking.